

## Connecting embedded systems to the cloud: Data ingress and analysis

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### Talk Summary:

The ubiquity of embedded devices has led to the situation that we now have sensors almost everywhere. Still, the scientific insights we gain from this wealth of sensor data is still limited as there are a number of challenges in the collection and analysis of these streams of data. While dedicated high performance ingest systems can be build, there is still the challenge to practically build a system dealing with a high number of sensors and high data rates over public internet connectivity.

This talk will give an overview on how cloud-based systems can be used to build performant data ingress and analysis for internet-connected devices in a research setting.



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